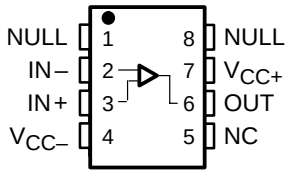
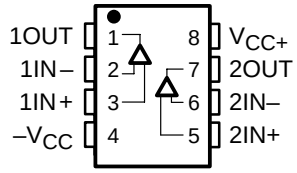
- **Ultra-Low 1.5 nV/√Hz Voltage Noise**
- **High Speed**
  - **350 MHz Bandwidth (G = 10, –3 dB)**
  - **470 V/μs Slew Rate**
  - **40 ns Settling Time (0.1%)**
- **Stable at a Gain of 10 (–9) or Greater**
- **High Output Drive, I_O = 100 mA (typ)**
- **Excellent Video Performance**
  - **17 MHz Bandwidth (0.1 dB, G = 10)**
  - **0.02% Differential Gain**
  - **0.08° Differential Phase**
- **Very Low Distortion**
  - **THD = –68 dBc (f = 1 MHz, R_L = 150 Ω)**
- **Wide Range of Power Supplies**
  - **V_{CC} = ±5 V to ±15 V**
- **Available in Standard SOIC or MSOP PowerPAD™ Package**
- **Evaluation Module Available**

THS4021
D AND DGN PACKAGE
(TOP VIEW)



THS4022
D AND DGN PACKAGE
(TOP VIEW)



NC – No internal connection

Cross Section View Showing
PowerPAD Option (DGN)

VOLTAGE & CURRENT NOISE
vs
FREQUENCY

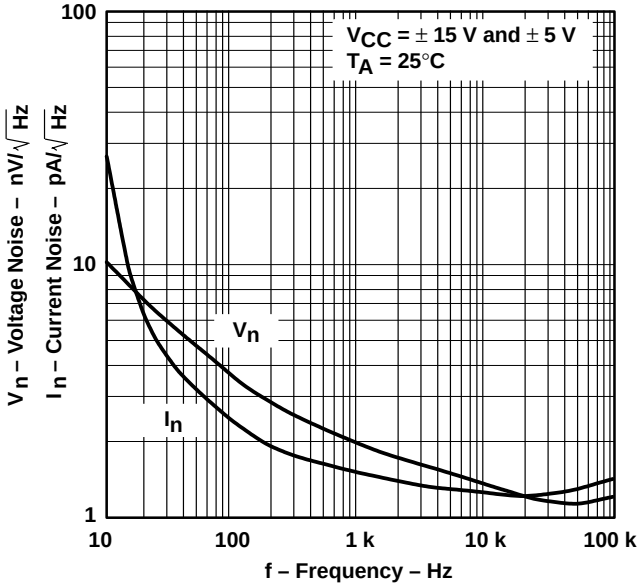


Figure 1

description

The THS4021 and THS4022 are ultra-low voltage noise, high-speed voltage feedback amplifiers that are ideal for applications requiring low voltage noise, including communication and imaging. The signal-amplifier THS4021 and the dual-amplifier THS4022 offer very good ac performance with 350-MHz bandwidth, 470-V/μs slew rate, and 40-ns settling time (0.1%). The THS4021 and THS4022 are stable at gains of 10 (–9) or greater. These amplifiers have a high drive capability of 100 mA and draw only 7.8-mA supply current per channel. With total harmonic distortion (THD) of –68 dBc at f = 1 MHz, the THS4021 and THS4022 are ideally suited for applications requiring low distortion.

RELATED DEVICES	
DEVICE	**DESCRIPTION**
THS4011/2	290-MHz Low Distortion High-Speed Amplifiers
THS4031/2	100-MHz Low Noise High-Speed Amplifiers
THS4061/2	180-MHz High-Speed Amplifiers

CAUTION: The THS4021 and THS4022 provide ESD protection circuitry. However, permanent damage can still occur if this device is subjected to high-energy electrostatic discharges. Proper ESD precautions are recommended to avoid any performance degradation or loss of functionality.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PowerPAD is a trademark of Texas Instruments Incorporated.

AVAILABLE OPTIONS

T_A	NUMBER OF CHANNELS	PACKAGED DEVICES		MSOP SYMBOL	EVALUATION MODULE
		PLASTIC SMALL OUTLINE† (D)	PLASTIC MSOP† (DGN)		
0°C to 70°C	1	THS4021CD	THS4021CDGN	ACK	THS4021EVM
	2	THS4022CD	THS4022CDGN	ACA	THS4022EVM
–40°C to 85°C	1	THS4021ID	THS4021IDGN	ACL	—
	2	THS4022ID	THS4022IDGN	ACB	—

† The D and DGN packages are available taped and reeled. Add an R suffix to the device type (i.e., THS4021CDGN).

functional block diagram

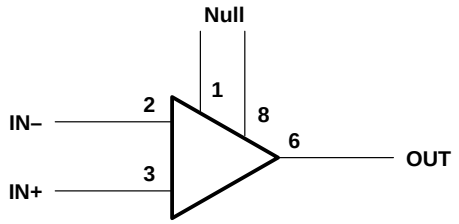


Figure 2. THS4021 – Single Channel

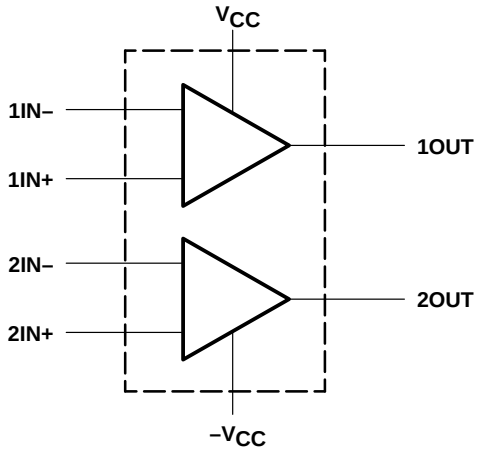


Figure 3. THS4022 – Dual Channel

absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage, V_{CC} . . . . . ±16.5 V
Input voltage, V_I . . . . . $\pm V_{CC}$
Output current, I_O . . . . . 150 mA
Differential input voltage, V_{IO} . . . . . ±4 V
Continuous total power dissipation . . . . . See Dissipation Rating Table
Maximum junction temperature, T_J . . . . . 150°C
Operating free-air temperature, T_A: C-suffix . . . . . 0°C to 70°C
I-suffix . . . . . –40°C to 85°C
Storage temperature, T_{stg} . . . . . –65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds . . . . . 300°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATING TABLE

PACKAGE	θ_{JA} (°C/W)	θ_{JC} (°C/W)	T_A = 25°C POWER RATING
D	167‡	38.3	740 mW
DGN§	58.4	4.7	2.14 W

‡ This data was taken using the JEDEC standard Low-K test PCB. For the JEDEC Proposed High-K test PCB, the θ_{JA} is 95°C/W with a power rating at T_A = 25°C of 1.32 W.
§ This data was taken using 2 oz. trace and copper pad that is soldered directly to a 3 in. × 3 in. PC. For further information, refer to *Application Information* section of this data sheet.

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V_{CC+} and V_{CC-}	Dual supply	±4.5		±16	V
	Single supply	9		32	
Operating free-air temperature, T_A	C-suffix	0		70	°C
	I-suffix	–40		85	

electrical characteristics at T_A = 25°C, V_{CC} = ±15 V, R_L = 150 Ω (unless otherwise noted)

dynamic performance

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT
BW	Small-signal bandwidth (–3 dB)	V_{CC} = ±15 V		Gain = 10		350		MHz
		V_{CC} = ±5 V				280		
		V_{CC} = ±15 V		Gain = 20		80		MHz
		V_{CC} = ±5 V				70		
	Bandwidth for 0.1 dB flatness	V_{CC} = ±15 V		Gain = 10		17		MHz
		V_{CC} = ±5 V				17		
	Full power bandwidth†	$V_{O(pp)}$ = 20 V,	V_{CC} = ±15 V			3.7		MHz
		$V_{O(pp)}$ = 5 V,	V_{CC} = ±5 V			11.8		
SR	Slew rate‡	V_{CC} = ±15 V,	10-V step,	Gain = 10		470		V/µs
		V_{CC} = ±5 V,	5-V step			370		
t_S	Settling time to 0.1%	V_{CC} = ±15 V,	5-V step	Gain = –10		40		ns
		V_{CC} = ±5 V,	2-V step			50		
	Settling time to 0.01%	V_{CC} = ±15 V,	5-V step	Gain = –10		145		ns
		V_{CC} = ±5 V,	2-V step			150		

† Slew rate is measured from an output level range of 25% to 75%.
‡ Full power bandwidth = slew rate / 2π $V_{O(Peak)}$.

noise/distortion performance

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT
THD	Total harmonic distortion	$V_{O(pp)}$ = 2 V, f = 1 MHz, Gain = 2	V_{CC} = ±15 V	R_L = 150 Ω		–68		dBc
				R_L = 1 kΩ		–77		
			V_{CC} = ±5 V	R_L = 150 Ω		–69		
				R_L = 1 kΩ		–78		
V_n	Input voltage noise	V_{CC} = ±5 V or ±15 V,	f = 10 kHz			1.5		nV/√Hz
I_n	Input current noise	V_{CC} = ±5 V or ±15 V,	f = 10 kHz			2		pA/√Hz
	Differential gain error	Gain = 2, 40 IRE modulation,	NTSC, ±100 IRE ramp	V_{CC} = ±15 V		0.02%		
				V_{CC} = ±5 V				
	Differential phase error	Gain = 2, 40 IRE modulation,	NTSC, ±100 IRE ramp	V_{CC} = ±15 V		0.08°		
				V_{CC} = ±5 V		0.06°		
X_T	Channel-to-channel crosstalk (THS4022 only)	V_{CC} = ±5 V or ±15 V,	f = 1 MHz			–60		dB

electrical characteristics at T_A = 25°C, V_{CC} = ±15 V, R_L = 150 Ω (unless otherwise noted) (continued)

dc performance

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT
	Open loop gain	V_{CC} = ±15 V, V_O = ±10 V, R_L = 1 kΩ		T_A = 25°C	40	60		V/mV
				T_A = full range	35			
		V_{CC} = ±5 V, V_O = ±2.5 V, R_L = 250 Ω		T_A = 25°C	20	35		V/mV
				T_A = full range	15			
V_{OS}	Input offset voltage	V_{CC} = ±5 V or ±15 V		T_A = 25°C		0.5	2	mV
				T_A = full range			3	
	Offset voltage drift			T_A = full range		15		µV/°C
I_{IB}	Input bias current			T_A = 25°C		3	6	µA
				T_A = full range			6	
I_{OS}	Input offset current			T_A = 25°C		30	250	nA
				T_A = full range			400	
	Offset current drift	T_A = full range				0.3		nA/°C

input characteristics

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT
V_{ICR}	Common-mode input voltage range	V_{CC} = ±15 V			±13.8	±14.3		V
		V_{CC} = ±5 V			±3.8	±4.3		
CMRR	Common mode rejection ratio	V_{CC} = ±15 V,	V_{ICR} = ±12 V,	T_A = full range	74	95		dB
r_i	Input resistance					1		MΩ
C_i	Input capacitance					1.5		pF

output characteristics

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
V_O	Output voltage swing	V_{CC} = ±15 V	R_L = 250 Ω	±12	±12.5		V
		V_{CC} = ±5 V	R_L = 150 Ω	±3	±3.3		
		V_{CC} = ±15 V	R_L = 1 kΩ	±13	±13.5		V
		V_{CC} = ±5 V		±3.4	±3.8		
I_O	Output current	V_{CC} = ±15 V	R_L = 20 Ω	80	100		mA
		V_{CC} = ±5 V		50	75		
I_{SC}	Short-circuit current†	V_{CC} = ±15 V			150		mA
R_O	Output resistance†	Open loop			13		Ω

† Observe power dissipation ratings to keep the junction temperature below the absolute maximum rating when the output is heavily loaded or shorted. See the absolute maximum ratings section of this data sheet for more information.

power supply

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT
V_{CC}	Supply voltage operating range	Dual supply			±4.5		±16.5	V
		Single supply			9		33	
I_{CC}	Supply current (per amplifier)	V_{CC} = ±15 V		T_A = 25°C		7.8	10	mA
				T_A = full range			11	
		V_{CC} = ±5 V		T_A = 25°C		6.7	9	
				T_A = full range			10.5	
PSRR	Power supply rejection ratio	V_{CC} = ±5 V or ±15 V		T_A = full range	80	95		dB

TYPICAL CHARACTERISTICS

CROSSTALK vs FREQUENCY

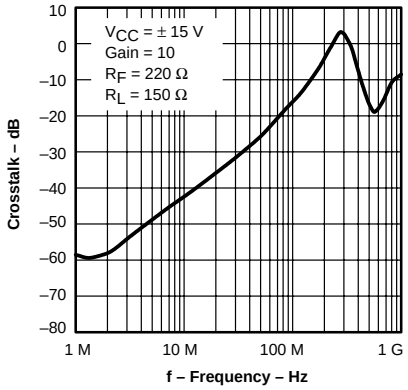


Figure 4

OPEN LOOP GAIN AND PHASE RESPONSE vs FREQUENCY

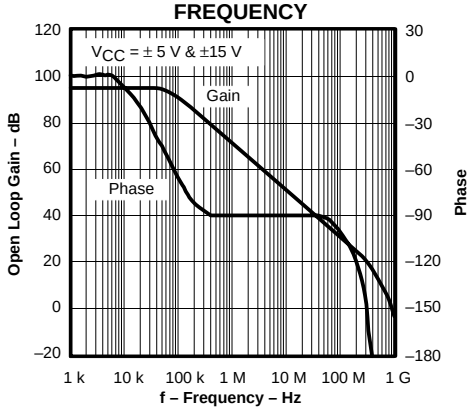


Figure 5

TOTAL HARMONIC DISTORTION vs FREQUENCY

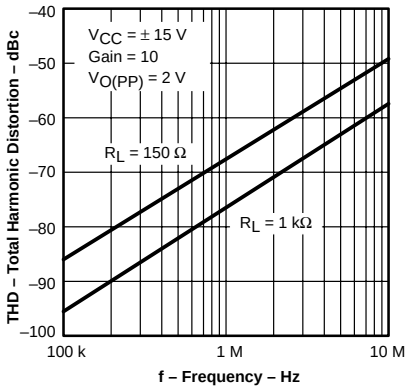


Figure 6

DISTORTION vs OUTPUT VOLTAGE

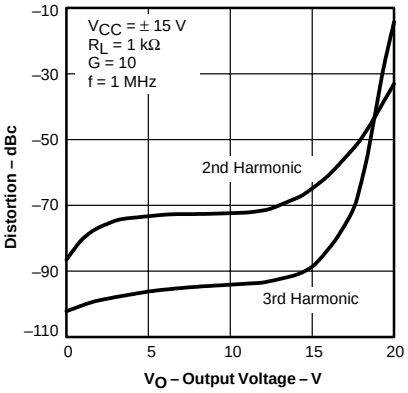


Figure 7

DISTORTION vs OUTPUT VOLTAGE

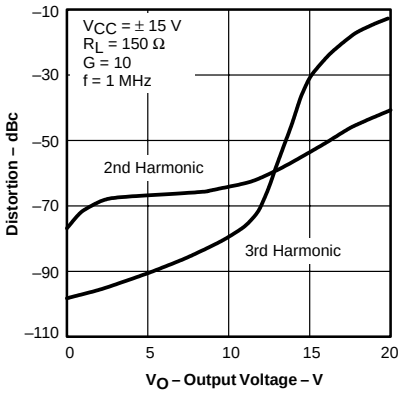


Figure 8

DISTORTION vs FREQUENCY

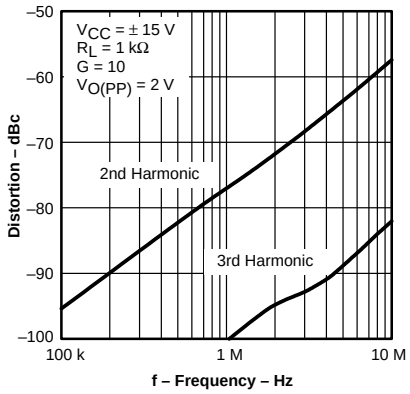


Figure 9

DISTORTION vs FREQUENCY

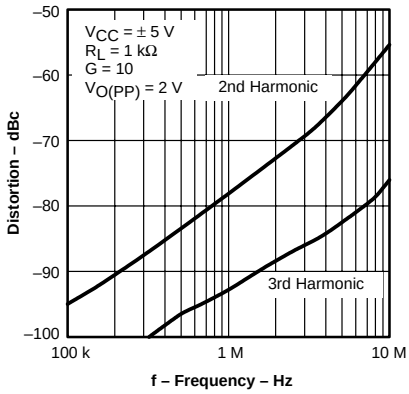


Figure 10

DISTORTION vs FREQUENCY

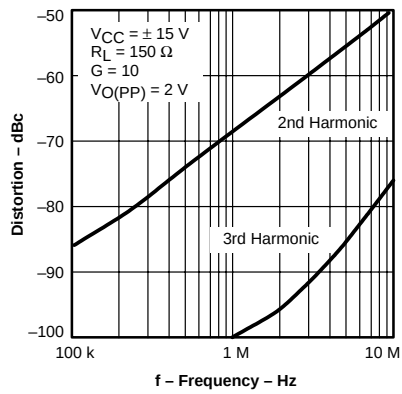


Figure 11

TYPICAL CHARACTERISTICS

DISTORTION vs FREQUENCY

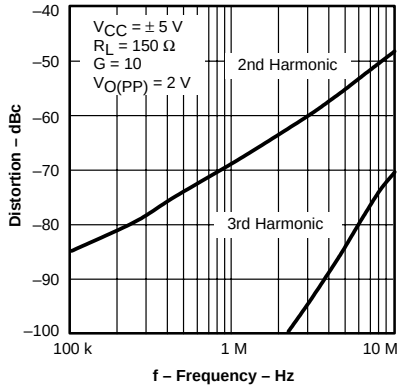


Figure 12

OUTPUT AMPLITUDE vs FREQUENCY

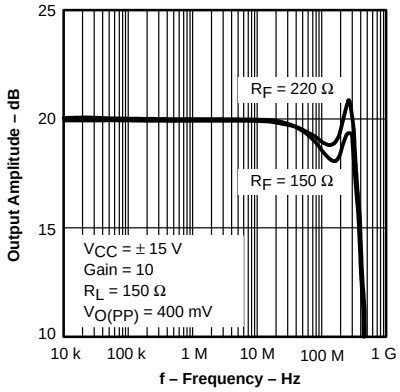


Figure 13

OUTPUT AMPLITUDE vs FREQUENCY

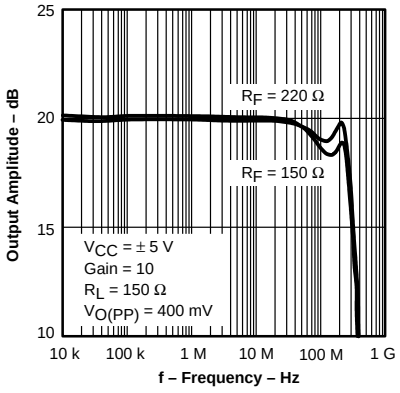


Figure 14

OUTPUT AMPLITUDE vs FREQUENCY

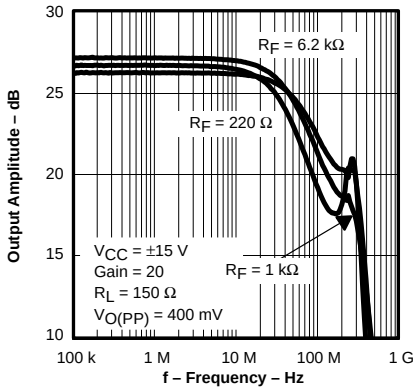


Figure 15

OUTPUT AMPLITUDE vs FREQUENCY

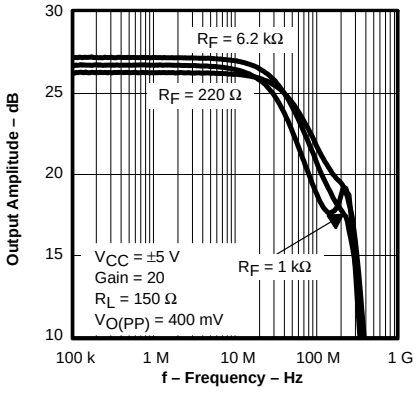


Figure 16

1-V STEP RESPONSE

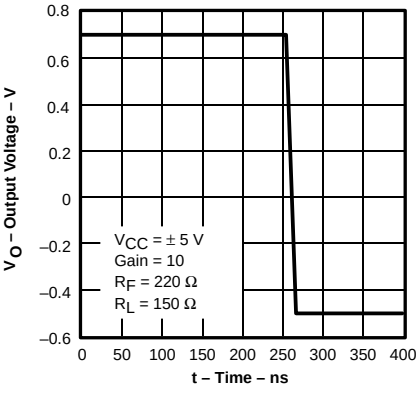


Figure 17

5-V STEP RESPONSE

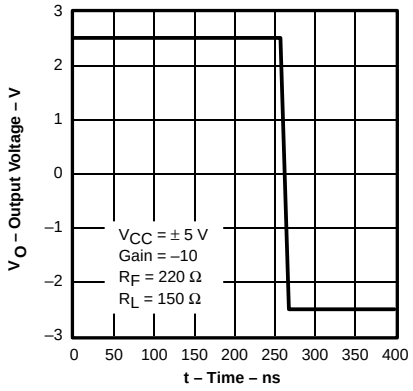


Figure 18

1-V STEP RESPONSE

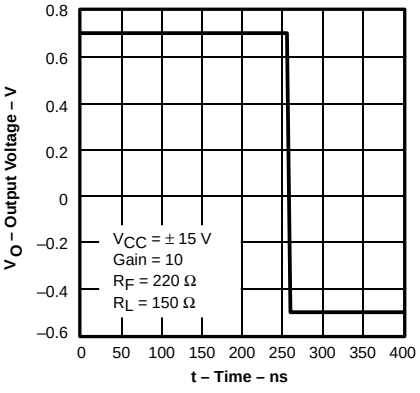


Figure 19

10-V STEP RESPONSE

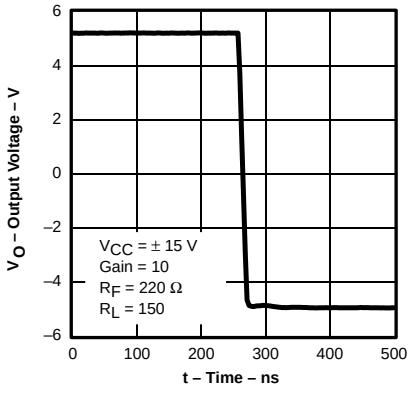


Figure 20

TYPICAL CHARACTERISTICS

INPUT OFFSET VOLTAGE vs FREE-AIR TEMPERATURE

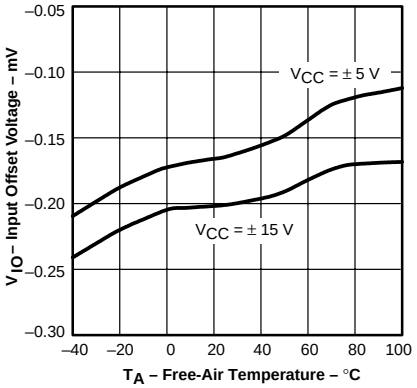


Figure 21

INPUT BIAS CURRENT vs FREE-AIR TEMPERATURE

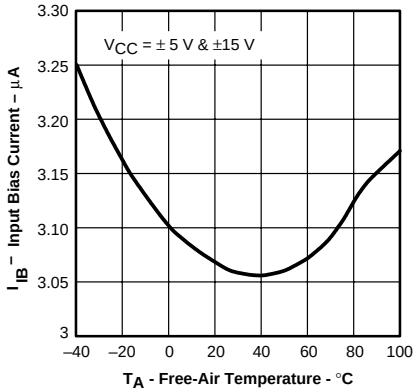


Figure 22

OUTPUT VOLTAGE vs SUPPLY VOLTAGE

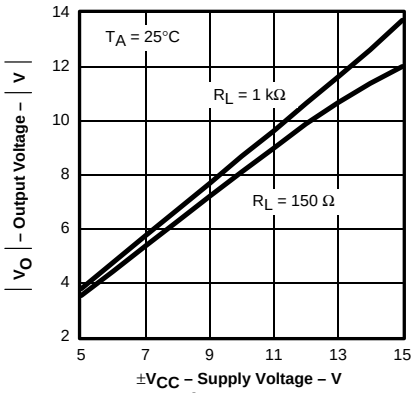


Figure 23

COMMON-MODE INPUT VOLTAGE vs SUPPLY VOLTAGE

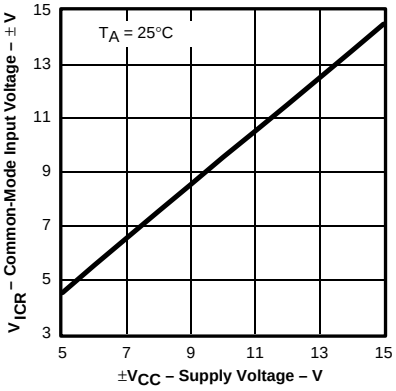


Figure 24

OUTPUT VOLTAGE vs FREE-AIR TEMPERATURE

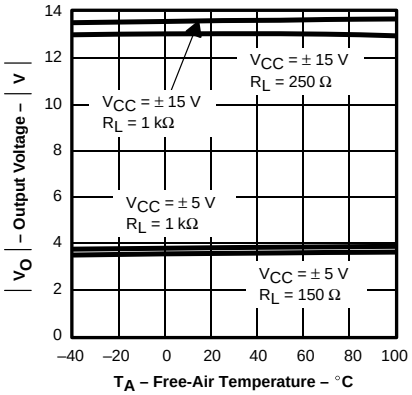


Figure 25

SUPPLY CURRENT vs SUPPLY VOLTAGE

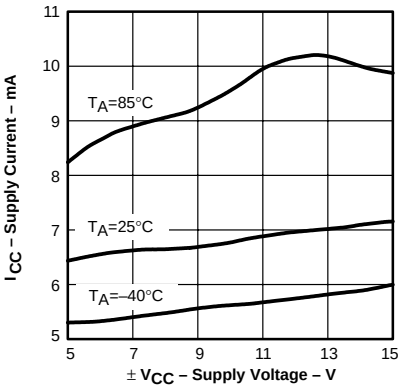


Figure 26

VOLTAGE & CURRENT NOISE vs FREQUENCY

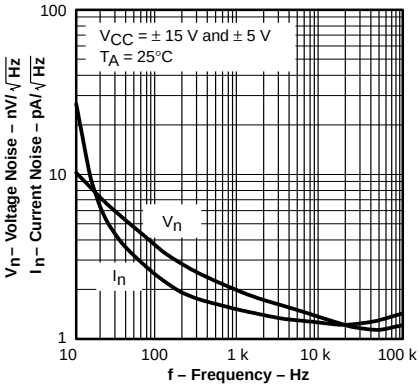


Figure 27

POWER SUPPLY REJECTION RATIO vs FREQUENCY

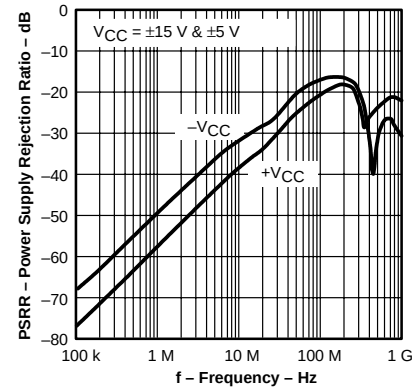


Figure 28

CMRR vs FREQUENCY

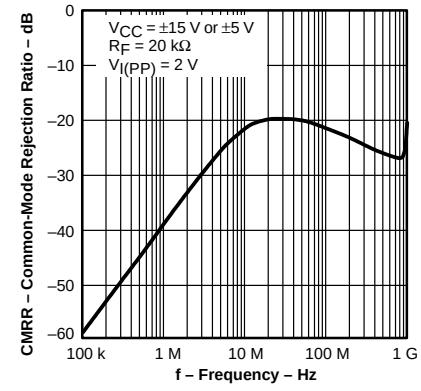


Figure 29

APPLICATION INFORMATION

theory of operation

The THS402x is a high-speed, operational amplifier configured in a voltage feedback architecture. It is built using a 30-V, dielectrically isolated, complementary bipolar process with NPN and PNP transistors possessing f_Ts of several GHz. This results in an exceptionally high performance amplifier that has a wide bandwidth, high slew rate, fast settling time, and low distortion. A simplified schematic is shown in Figure 30.

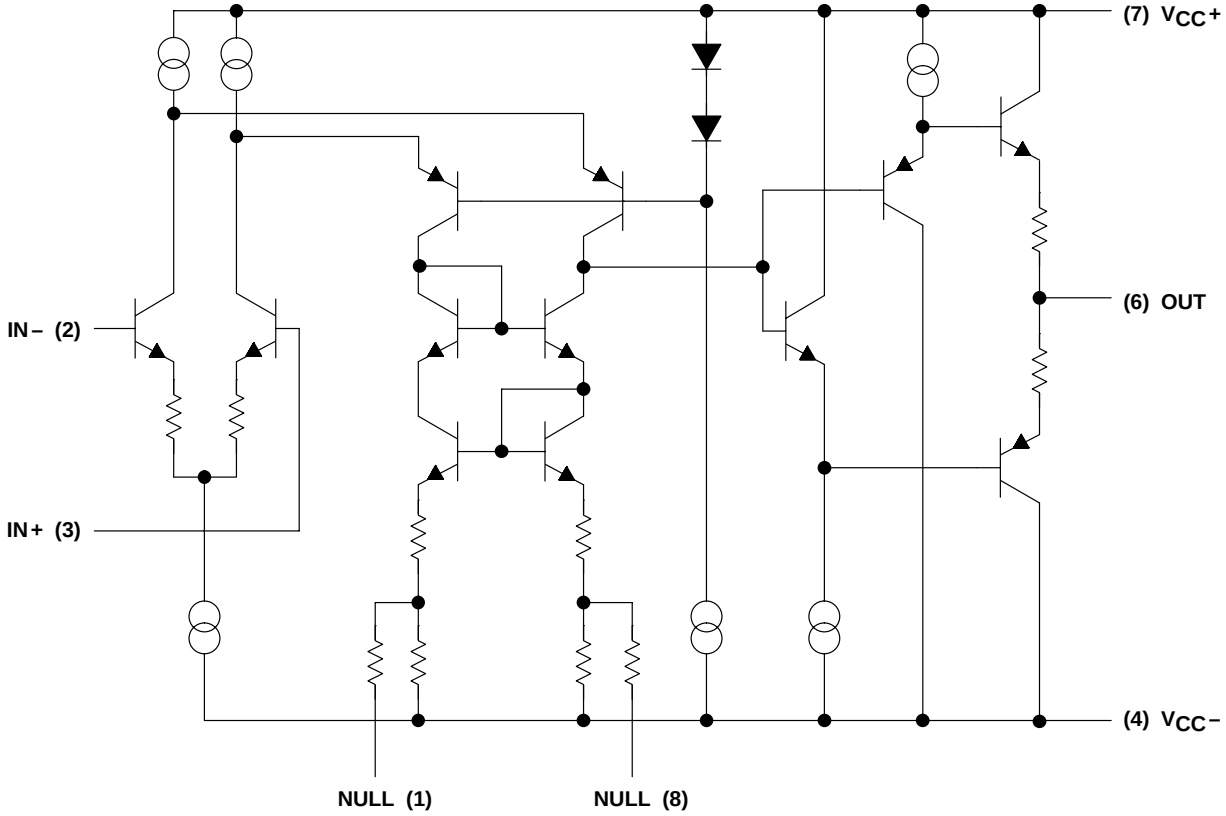


Figure 30. THS4021 Simplified Schematic

noise calculations and noise figure

Noise can cause errors on very small signals. This is especially true when amplifying small signals, where signal-to-noise ratio (SNR) is very important. The noise model for the THS402x is shown in Figure 31. This model includes all of the noise sources as follows:

- e_n = Amplifier internal voltage noise (nV/$\sqrt{Hz}$)
- IN+ = Noninverting current noise (pA/$\sqrt{Hz}$)
- IN– = Inverting current noise (pA/$\sqrt{Hz}$)
- e_{Rx} = Thermal voltage noise associated with each resistor (e_{Rx} = 4 kTR_x)

APPLICATION INFORMATION

noise calculations and noise figure (continued)

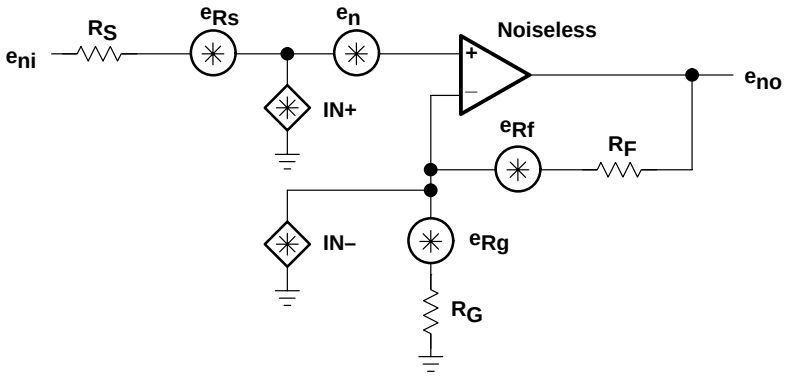


Figure 31. Noise Model

The total equivalent input noise density (e_{ni}) is calculated by using the following equation:

$$e_{ni} = \sqrt{(e_n)^2 + \left(IN + \times R_S\right)^2 + \left(IN- \times \left(R_F \parallel R_G\right)\right)^2 + 4\ kTR_S + 4\ kT\left(R_F \parallel R_G\right)}$$

Where:

k = Boltzmann's constant = 1.380658×10^{-23}
T = Temperature in degrees Kelvin (273 +°C)
R_F || R_G = Parallel resistance of R_F and R_G

To get the equivalent output noise of the amplifier, just multiply the equivalent input noise density (e_{ni}) by the overall amplifier gain (A_V).

$$e_{no} = e_{ni}\ A_V = e_{ni}\left(1 + \frac{R_F}{R_G}\right) \text{ (noninverting case)}$$

As the previous equations show, to keep noise at a minimum, small value resistors should be used. As the closed-loop gain is increased (by reducing R_G), the input noise is reduced considerably because of the parallel resistance term. This leads to the general conclusion that the most dominant noise sources are the source resistor (R_S) and the internal amplifier noise voltage (e_n). Because noise is summed in a root-mean-squares method, noise sources smaller than 25% of the largest noise source can be effectively ignored. This can greatly simplify the formula and make noise calculations much easier to calculate.

For more information on noise analysis, please refer to the *Noise Analysis* section in *Operational Amplifier Circuits Applications Report* (literature number SLVA043).

APPLICATION INFORMATION

noise calculations and noise figure (continued)

This brings up another noise measurement usually preferred in RF applications, the noise figure (NF). Noise figure is a measure of noise degradation caused by the amplifier. The value of the source resistance must be defined and is typically 50 Ω in RF applications.

$$NF = 10\log\left[\frac{e_{ni}^{2}}{\left(e_{Rs}\right)^{2}}\right]$$

Because the dominant noise components are generally the source resistance and the internal amplifier noise voltage, we can approximate noise figure as:

$$NF = 10\log\left[1 + \frac{\left[\left(e_{n}\right)^{2} + \left(IN + \times R_{S}\right)^{2}\right]}{4\ kTR_{S}}\right]$$

Figure 32 shows the noise figure graph for the THS402x.

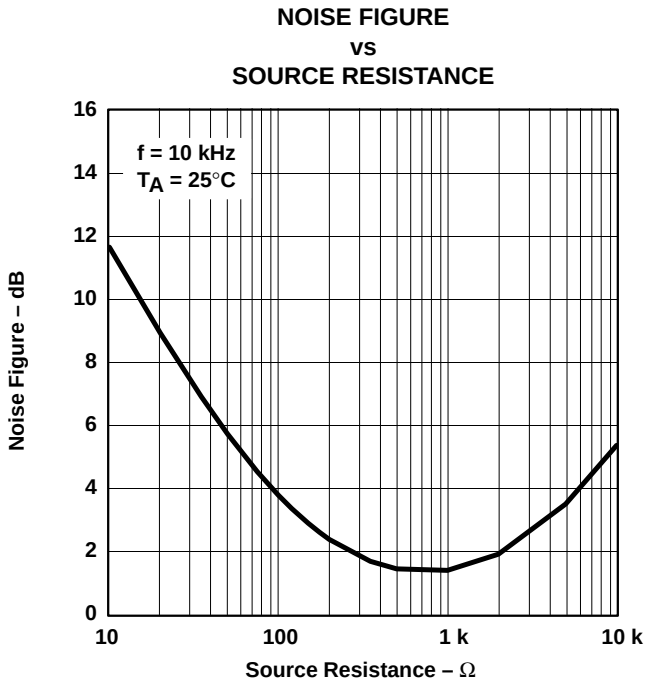


Figure 32. Noise Figure vs Source Resistance

APPLICATION INFORMATION

driving a capacitive load

Driving capacitive loads with high performance amplifiers is not a problem as long as certain precautions are taken. The first is to realize that the THS402x has been internally compensated to maximize its bandwidth and slew rate performance. When the amplifier is compensated in this manner, capacitive loading directly on the output will decrease the device's phase margin leading to high frequency ringing or oscillations. Therefore, for capacitive loads of greater than 10 pF, it is recommended that a resistor be placed in series with the output of the amplifier, as shown in Figure 33. A minimum value of 20 Ω should work well for most applications. For example, in 75-Ω transmission systems, setting the series resistor value to 75 Ω both isolates any capacitance loading and provides the proper line impedance matching at the source end.

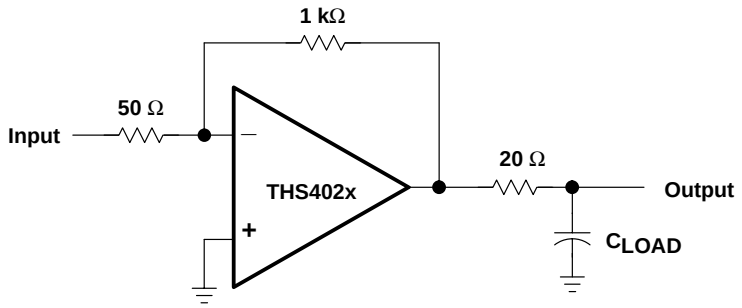


Figure 33. Driving a Capacitive Load

offset nulling

The THS402x has very low input offset voltage for a high-speed amplifier. However, if additional correction is required, an offset nulling function has been provided on the THS4021. The input offset can be adjusted by placing a potentiometer between terminals 1 and 8 of the device and tying the wiper to the negative supply. This is shown in Figure 34.

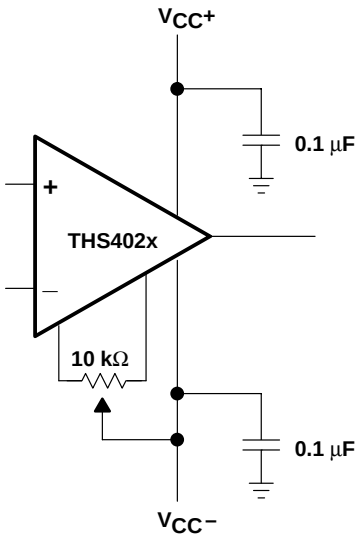
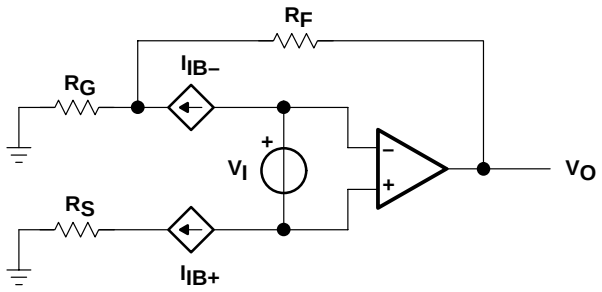


Figure 34. Offset Nulling Schematic

APPLICATION INFORMATION

offset voltage

The output offset voltage, (V_{OO}) is the sum of the input offset voltage (V_{IO}) and both input bias currents (I_{IB}) times the corresponding gains. The following schematic and formula can be used to calculate the output offset voltage:

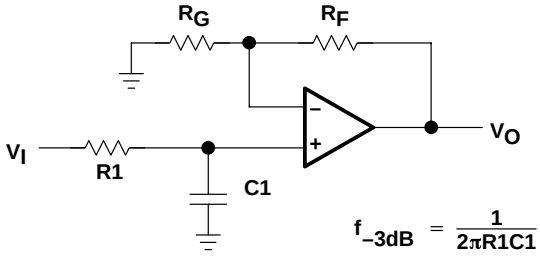


$$V_{OO} = V_{IO}\left(1 + \left(\frac{R_F}{R_G}\right)\right) \pm I_{IB+}\ R_S\left(1 + \left(\frac{R_F}{R_G}\right)\right) \pm I_{IB-}\ R_F$$

Figure 35. Output Offset Voltage Model

general configurations

When receiving low-level signals, limiting the bandwidth of the incoming signals into the system is often required. The simplest way to accomplish this is to place an RC filter at the noninverting terminal of the amplifier (see Figure 36).



$$f_{-3dB} = \frac{1}{2\pi R1C1}$$

$$\frac{V_O}{V_I} = \left(1 + \frac{R_F}{R_G}\right)\left(\frac{1}{1 + sR1C1}\right)$$

Figure 36. Single-Pole Low-Pass Filter

APPLICATION INFORMATION

circuit layout considerations

To achieve the levels of high frequency performance of the THS402x, follow proper printed-circuit board high frequency design techniques. A general set of guidelines is given below. In addition, a THS402x evaluation board is available to use as a guide for layout or for evaluating the device performance.

- Ground planes – It is highly recommended that a ground plane be used on the board to provide all components with a low inductive ground connection. However, in the areas of the amplifier inputs and output, the ground plane can be removed to minimize the stray capacitance.
- Proper power supply decoupling – Use a 6.8-μF tantalum capacitor in parallel with a 0.1-μF ceramic capacitor on each supply terminal. It may be possible to share the tantalum among several amplifiers depending on the application, but a 0.1-μF ceramic capacitor should always be used on the supply terminal of every amplifier. In addition, the 0.1-μF capacitor should be placed as close as possible to the supply terminal. As this distance increases, the inductance in the connecting trace makes the capacitor less effective. The designer should strive for distances of less than 0.1 inches between the device power terminals and the ceramic capacitors.
- Sockets – Sockets are not recommended for high-speed operational amplifiers. The additional lead inductance in the socket pins will often lead to stability problems. Surface-mount packages soldered directly to the printed-circuit board is the best implementation.
- Short trace runs/compact part placements – Optimum high frequency performance is achieved when stray series inductance has been minimized. To realize this, the circuit layout should be made as compact as possible, thereby minimizing the length of all trace runs. Particular attention should be paid to the inverting input of the amplifier. Its length should be kept as short as possible. This will help to minimize stray capacitance at the input of the amplifier.
- Surface-mount passive components – Using surface-mount passive components is recommended for high frequency amplifier circuits for several reasons. First, because of the extremely low lead inductance of surface-mount components, the problem with stray series inductance is greatly reduced. Second, the small size of surface-mount components naturally leads to a more compact layout, thereby minimizing both stray inductance and capacitance. If leaded components are used, it is recommended that the lead lengths be kept as short as possible.

general PowerPAD design considerations

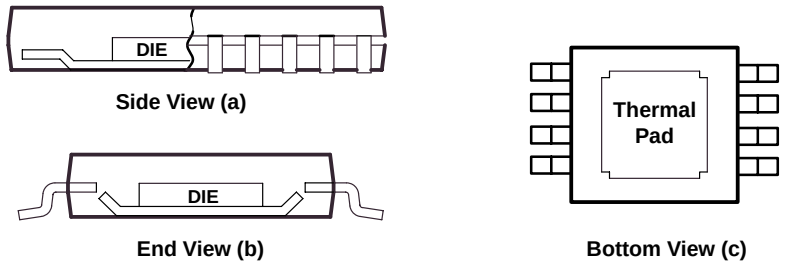
The THS402x is available packaged in a thermally-enhanced DGN package, which is a member of the PowerPAD family of packages. This package is constructed using a downset leadframe upon which the die is mounted [see Figure 37(a) and Figure 37(b)]. This arrangement results in the lead frame being exposed as a thermal pad on the underside of the package [see Figure 37(c)]. Because this thermal pad has direct thermal contact with the die, excellent thermal performance can be achieved by providing a good thermal path away from the thermal pad.

The PowerPAD package allows for both assembly and thermal management in one manufacturing operation. During the surface-mount solder operation (when the leads are being soldered), the thermal pad can also be soldered to a copper area underneath the package. Through the use of thermal paths within this copper area, heat can be conducted away from the package into either a ground plane or other heat dissipating device.

The PowerPAD package represents a breakthrough in combining the small area and ease of assembly of the surface mount with the, heretofore, awkward mechanical methods of heatsinking.

APPLICATION INFORMATION

general PowerPAD design considerations (continued)



NOTE A: The thermal pad is electrically isolated from all terminals in the package.

Figure 37. Views of Thermally Enhanced DGN Package

Although there are many ways to properly heatsink this device, the following steps illustrate the recommended approach.

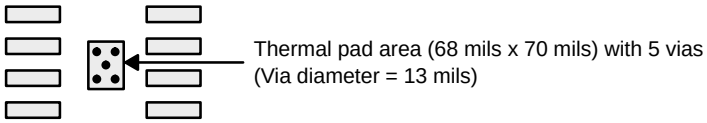


Figure 38. PowerPAD PCB Etch and Via Pattern

1. Prepare the PCB with a top side etch pattern as shown in Figure 38. There should be etch for the leads as well as etch for the thermal pad.
2. Place five holes in the area of the thermal pad. These holes should be 13 mils in diameter. Keep them small so that solder wicking through the holes is not a problem during reflow.
3. Additional vias may be placed anywhere along the thermal plane outside of the thermal pad area. This helps dissipate the heat generated by the THS402xDGN IC. These additional vias may be larger than the 13-mil diameter vias directly under the thermal pad. They can be larger because they are not in the thermal pad area to be soldered, so wicking is not a problem.
4. Connect all holes to the internal ground plane.
5. When connecting these holes to the ground plane, do not use the typical web or spoke via connection methodology. Web connections have a high thermal resistance connection that is useful for slowing the heat transfer during soldering operations. This makes the soldering of vias that have plane connections easier. In this application, however, low thermal resistance is desired for the most efficient heat transfer. Therefore, the holes under the THS402xDGN package should make their connection to the internal ground plane with a complete connection around the entire circumference of the plated-through hole.
6. The top-side solder mask should leave the terminals of the package and the thermal pad area with its five holes exposed. The bottom-side solder mask should cover the five holes of the thermal pad area. This prevents solder from being pulled away from the thermal pad area during the reflow process.
7. Apply solder paste to the exposed thermal pad area and all of the IC terminals.
8. With these preparatory steps in place, the THS402xDGN IC is simply placed in position and run through the solder reflow operation as any standard surface-mount component. This results in a part that is properly installed.

APPLICATION INFORMATION

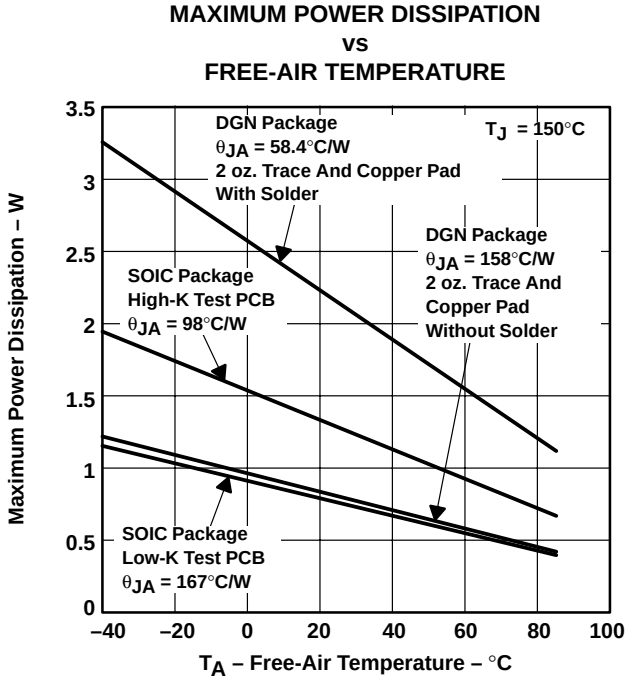
general PowerPAD design considerations (continued)

The actual thermal performance achieved with the THS402xDGN in its PowerPAD package depends on the application. In the example above, if the size of the internal ground plane is approximately 3 inches × 3 inches, then the expected thermal coefficient, θ_{JA}, is about 58.4°C/W. For comparison, the non-PowerPAD version of the THS402x IC (SOIC) is shown. For a given θ_{JA}, the maximum power dissipation is shown in Figure 39 and is calculated by the following formula:

$$P_D = \left(\frac{T_{MAX} - T_A}{\theta_{JA}} \right)$$

Where:

P_D = Maximum power dissipation of THS402x IC (watts)
T_{MAX} = Absolute maximum junction temperature (150°C)
T_A = Free-ambient air temperature (°C)
$\theta_{JA} = \theta_{JC} + \theta_{CA}$
θ_{JC} = Thermal coefficient from junction to case
θ_{CA} = Thermal coefficient from case to ambient air (°C/W)



NOTE A: Results are with no air flow and PCB size = 3”× 3”

Figure 39. Maximum Power Dissipation vs Free-Air Temperature

More complete details of the PowerPAD installation process and thermal management techniques can be found in the Texas Instruments Technical Brief, *PowerPAD Thermally Enhanced Package.* This document can be found at the TI web site (www.ti.com) by searching on the key word PowerPAD. The document can also be ordered through your local TI sales office. Refer to literature number SLMA002 when ordering.

APPLICATION INFORMATION

general PowerPAD design considerations (continued)

The next consideration is the package constraints. The two sources of heat within an amplifier are quiescent power and output power. The designer should never forget about the quiescent heat generated within the device, especially multiamplifier devices. Because these devices have linear output stages (Class A-B), most of the heat dissipation is at low output voltages with high output currents. Figure 40 to Figure 43 show this effect, along with the quiescent heat, with an ambient air temperature of 50°C. Obviously, as the ambient temperature increases, the limit lines shown will drop accordingly. The area under each respective limit line is considered the safe operating area. Any condition above this line will exceed the amplifier's limits and failure may result. When using V_{CC} = ±5 V, there is generally not a heat problem, even with SOIC packages. But, when using V_{CC} = ±15 V, the SOIC package is severely limited in the amount of heat it can dissipate. The other key factor when looking at these graphs is how the devices are mounted on the PCB. The PowerPAD devices are extremely useful for heat dissipation. But, the device should always be soldered to a copper plane to fully use the heat dissipation properties of the PowerPAD. The SOIC package, on the other hand, is highly dependent on how it is mounted on the PCB. As more trace and copper area is placed around the device, θ_{JA} decreases and the heat dissipation capability increases. The currents and voltages shown in these graphs are for the total package. For the dual amplifier package (THS4022), the sum of the RMS output currents and voltages should be used to choose the proper package. The graphs shown assume that both amplifier's outputs are identical.

THS4021
MAXIMUM RMS OUTPUT CURRENT
vs
RMS OUTPUT VOLTAGE DUE TO THERMAL LIMITS

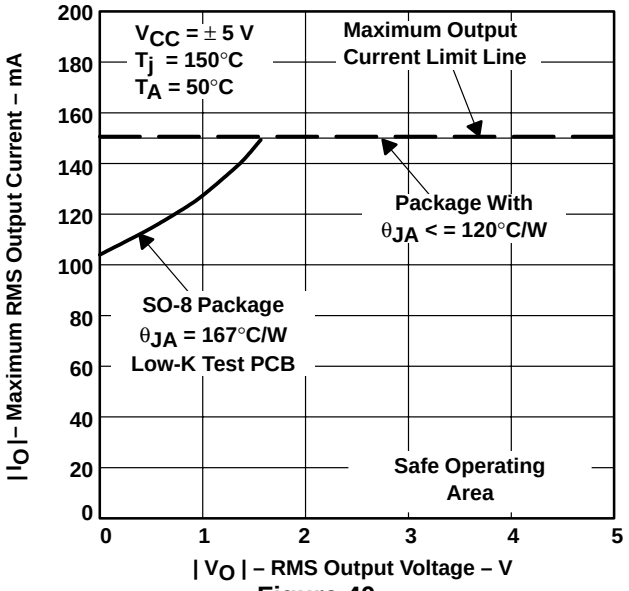


Figure 40

THS4021
MAXIMUM RMS OUTPUT CURRENT
vs
RMS OUTPUT VOLTAGE DUE TO THERMAL LIMITS

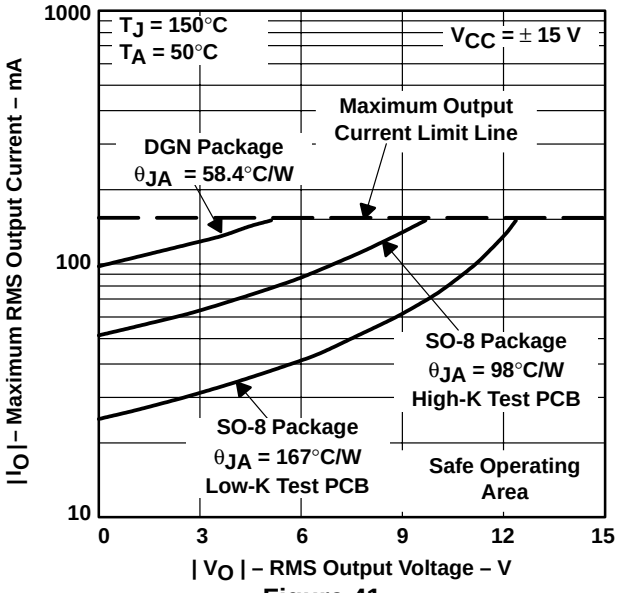


Figure 41

APPLICATION INFORMATION

general PowerPAD design considerations (continued)

THS4022
MAXIMUM RMS OUTPUT CURRENT
vs
RMS OUTPUT VOLTAGE DUE TO THERMAL LIMITS

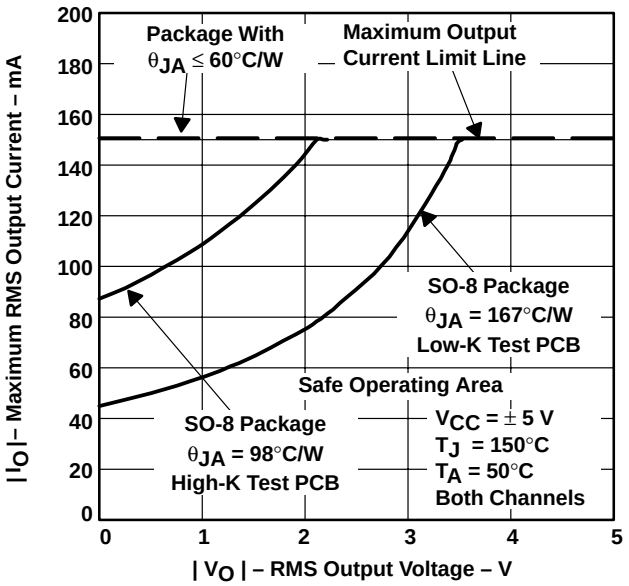


Figure 42

THS4022
MAXIMUM RMS OUTPUT CURRENT
vs
RMS OUTPUT VOLTAGE DUE TO THERMAL LIMITS

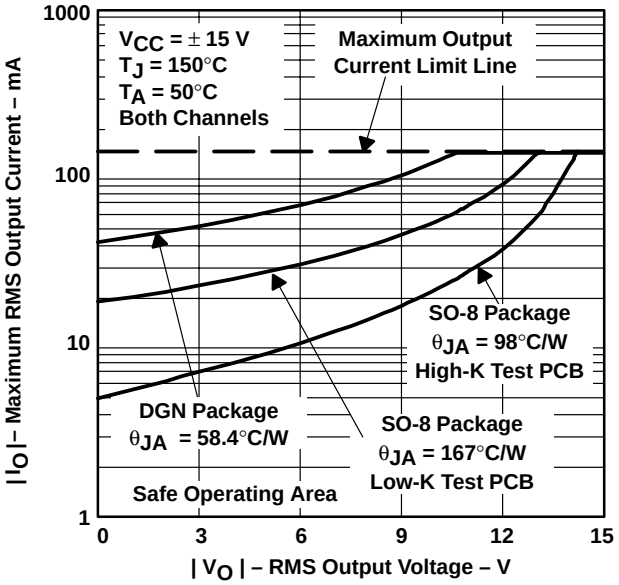


Figure 43

APPLICATION INFORMATION

evaluation board

An evaluation board is available for the THS4021 (literature number SLOP129) and THS4022 (literature number SLOP231). This board has been configured for very low parasitic capacitance in order to realize the full performance of the amplifier. A schematic of the evaluation board is shown in Figure 44. The circuitry has been designed so that the amplifier may be used in either an inverting or noninverting configuration. For more information, please refer to the *THS4021 EVM User's Guide* or the *THS4022 EVM User's Guide*. To order the evaluation board, contact your local TI sales office or distributor.

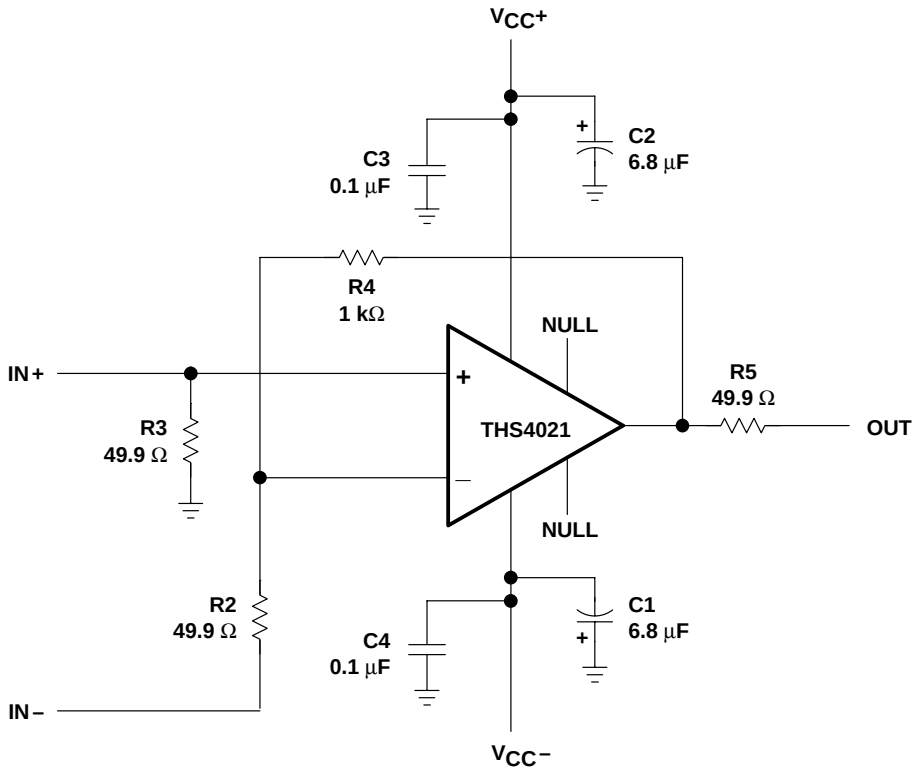
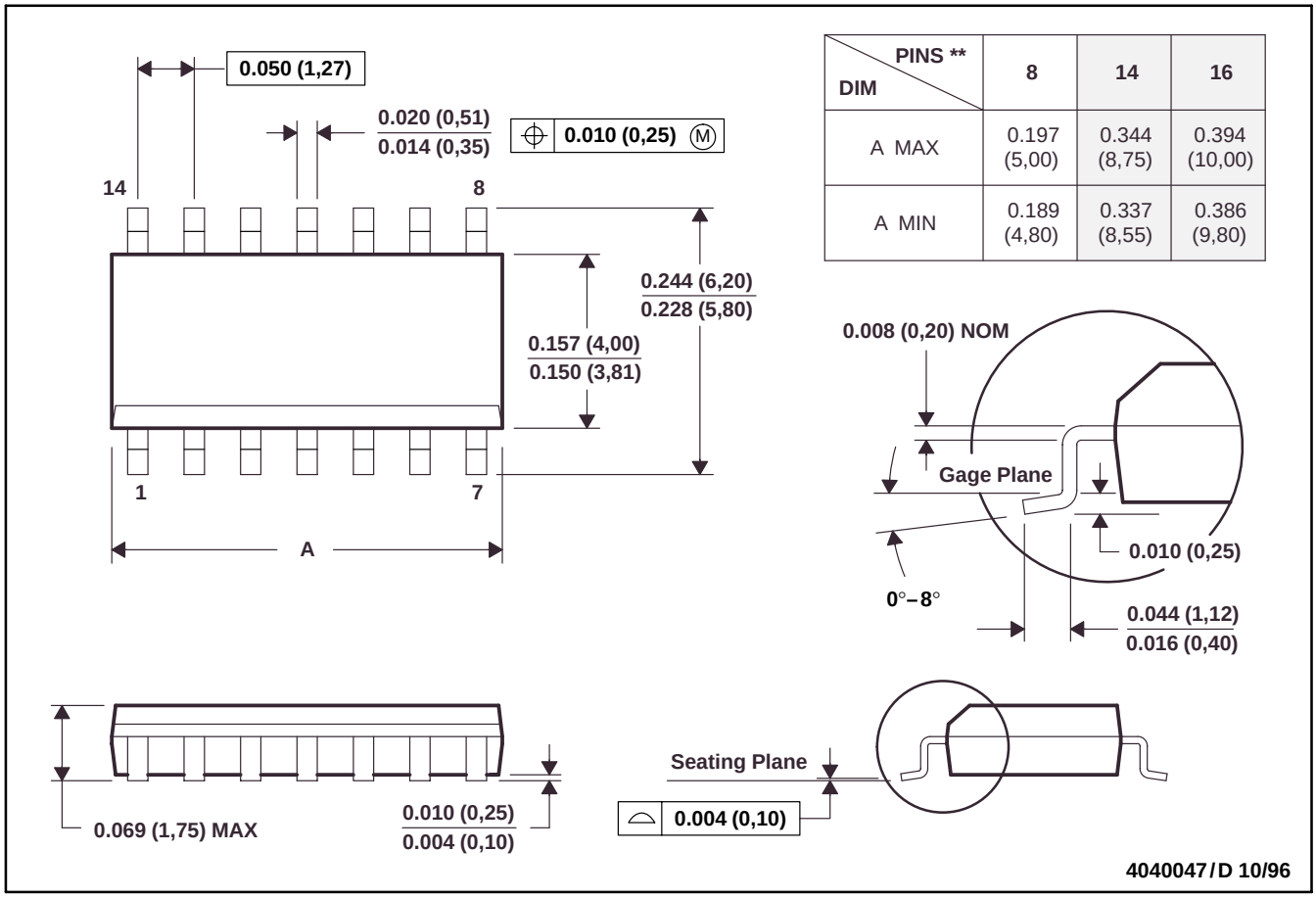


Figure 44. THS4021 Evaluation Board

MECHANICAL INFORMATION

D (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14 PIN SHOWN

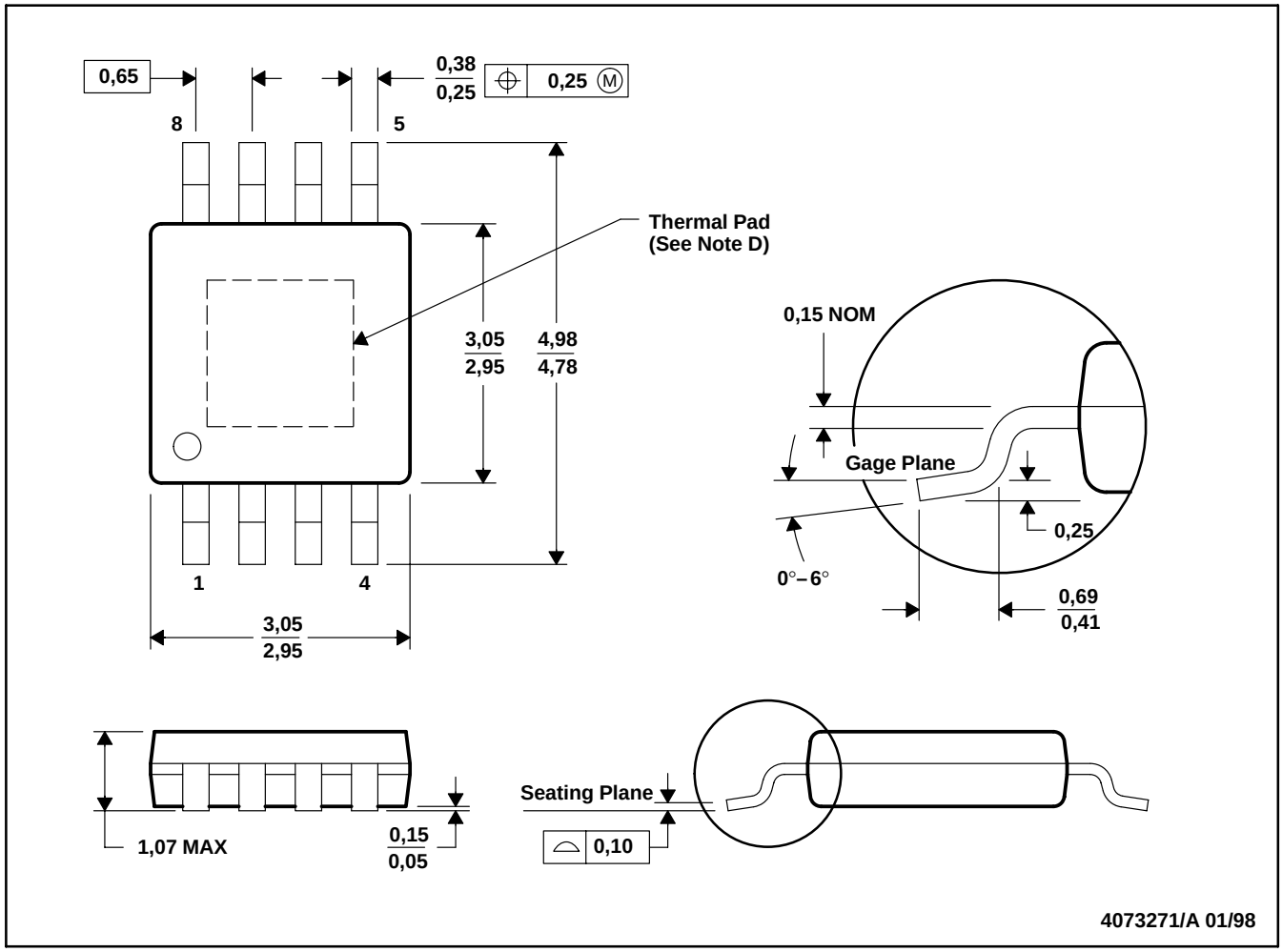


DIM \ PINS **	8	14	16
A MAX	0.197 (5,00)	0.344 (8,75)	0.394 (10,00)
A MIN	0.189 (4,80)	0.337 (8,55)	0.386 (9,80)

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
D. Falls within JEDEC MS-012

MECHANICAL INFORMATION

DGN (S-PDSO-G8) **PowerPAD™ PLASTIC SMALL-OUTLINE PACKAGE**



NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions include mold flash or protrusions.
D. The package thermal performance may be enhanced by attaching an external heat sink to the thermal pad. This pad is electrically and thermally connected to the backside of the die and possibly selected leads.
E. Falls within JEDEC MO-187

PowerPAD is a trademark of Texas Instruments Incorporated.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
THS4021CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4021CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4021CDGN	ACTIVE	MSOP-Power PAD	DGN	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4021CDGNG4	ACTIVE	MSOP-Power PAD	DGN	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4021CDGNR	ACTIVE	MSOP-Power PAD	DGN	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4021CDGNRG4	ACTIVE	MSOP-Power PAD	DGN	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4021CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4021CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4021ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4021IDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4021IDGN	ACTIVE	MSOP-Power PAD	DGN	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4021IDGNG4	ACTIVE	MSOP-Power PAD	DGN	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4021IDGNR	ACTIVE	MSOP-Power PAD	DGN	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4021IDGNRG4	ACTIVE	MSOP-Power PAD	DGN	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4021IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4021IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4022CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4022CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4022CDGN	ACTIVE	MSOP-Power PAD	DGN	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4022CDGNG4	ACTIVE	MSOP-Power PAD	DGN	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4022CDGNR	ACTIVE	MSOP-	DGN	8	2500	Green (RoHS &	CU NIPDAU	Level-1-260C-UNLIM

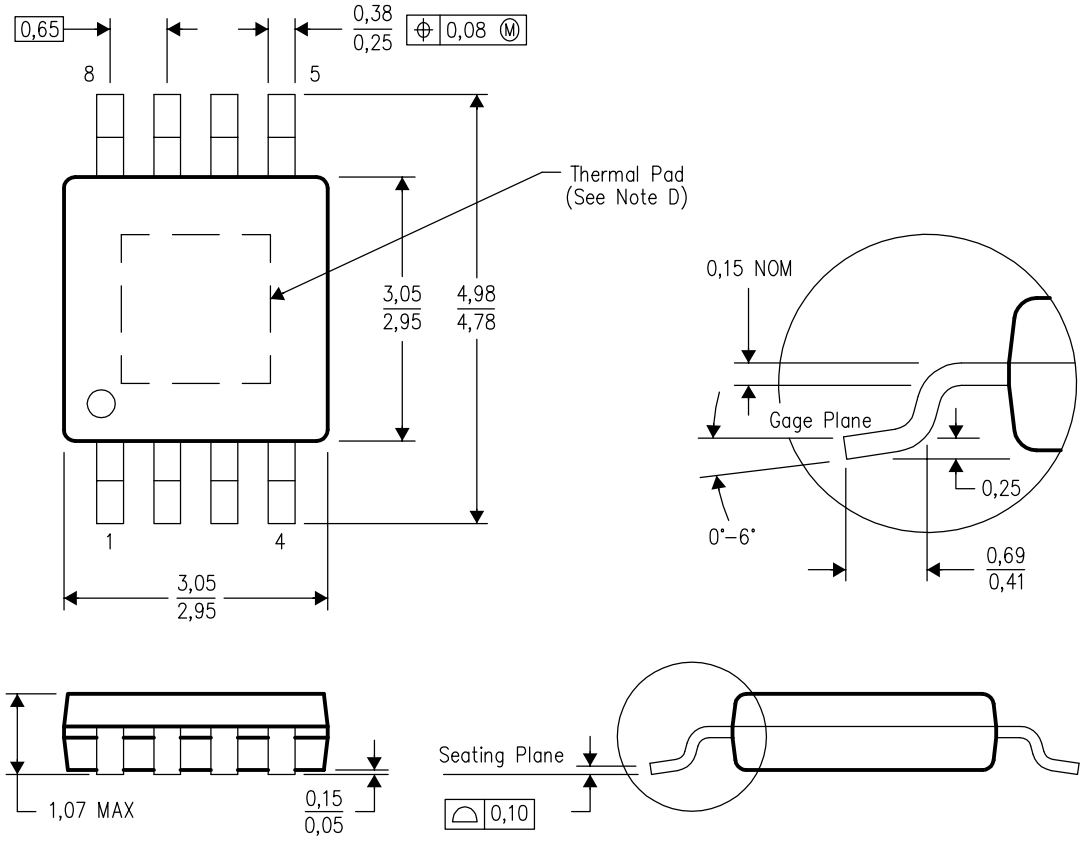
Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
		Power PAD				no Sb/Br)		
THS4022CDGNRG4	ACTIVE	MSOP-Power PAD	DGN	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4022CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4022CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4022ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4022IDGN	ACTIVE	MSOP-Power PAD	DGN	8	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4022IDGNR	ACTIVE	MSOP-Power PAD	DGN	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4022IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
THS4022IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

DGN (S–PDSO–G8) PowerPAD™ PLASTIC SMALL–OUTLINE PACKAGE

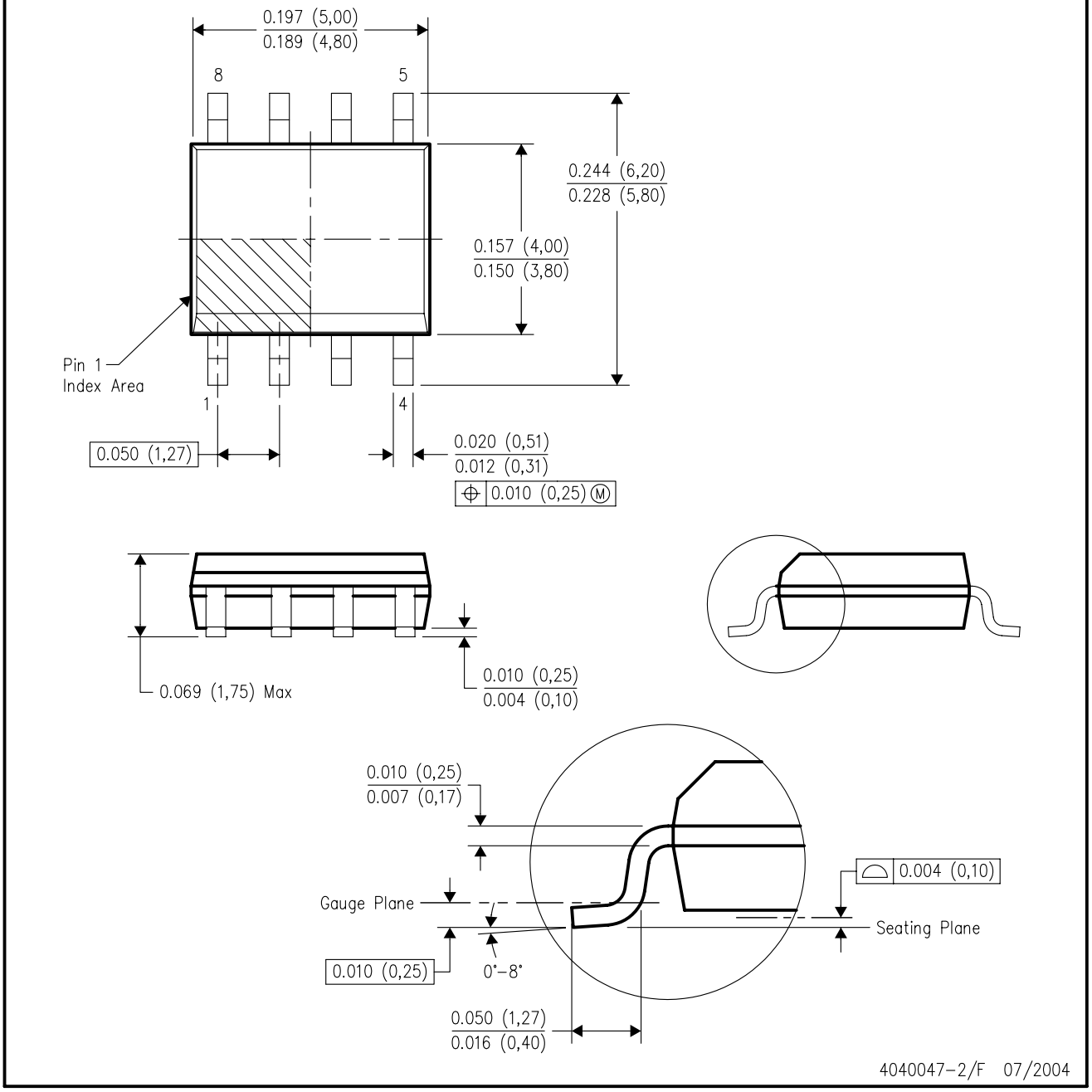


4073271/C 08/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion.
D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <http://www.ti.com>.
E. Falls within JEDEC MO–187

PowerPAD is a trademark of Texas Instruments.

D (R–PDSO–G8) PLASTIC SMALL–OUTLINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–012 variation AA.

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